



FRI 09:34 FAX 886 2 23697233

JIANQ CHYUN IPO

001

Customer No.: 31561
Docket No. 10320-US-PA
Application No.: 10/605,012

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Hung
Application No. : 10/605,012
Filed : 2003/9/1
For : STRUCTURE OF FLIP CHIP PACKAGE WITH AREA
BUMP
Art Unit : 2812
Examiner : ROMAN, ANGEL

TRANSMITTAL LETTER

002-1-703-746-4000

(Via fax: 1+4 pages)

Assistant Commissioner for Patents
Arlington, Virginia 22202

Dear Sir,

In response to the Notice of Allowance and Fee(s) due, dated July 22, 2004, transmitted herewith please find the Issue Fee Transmittal (PTOL-85B) in duplicate.

Enclosed herewith please find two sheets of corrected drawing in reply to the requirement made in the Office Action dated February 20, 2004.

Please charge the fee in the amount of \$1679.00 for Issue Fee, Publication Fee and 3 soft copies to Account No. 50-2620 (Order No.: 10320-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date:

By: Oct. 21, 2004
Belinda Lee
Registration No.: 46,863

Please send future correspondence to:

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